

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	IS&R	L1	5	((("5592025") or ("4460537") or ("5132778") or ("5136366") or ("5153385"))).PN.	USPAT	2005/03/16 13:27
2	BRS	L2	1384	(semiconductor or chip or die) and ((bump or ball) same heat) and ((bump or ball) same signal)	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2005/03/16 15:26
3	BRS	L3	22	("20010008305"   "5220490"   "5410107"   "5508556"   "5801440"   "5818102"   "5841191"   "5864470"   "5866942"   "5894410"   "5903050"   "5982632"   "6034427"   "6037677"   "6057596"   "6104258"   "6137168"   "6198635"   "6214638"   "6268238"   "6274925"   "6278264").PN.	US- PGPUB; USPAT; USOCR	2005/03/16 13:59
4	BRS	L4	14	("5483099"   "5490040"   "5502278"   "5545923"   "5554881"   "5640048"   "5641988"   "5691568"   "5714801"   "5717245"   "5719439"   "5719449"   "5796170"   "5955789").PN.	US- PGPUB; USPAT; USOCR	2005/03/16 14:12
5	BRS	L5	6	("6225702").URPN.	USPAT	2005/03/16 14:14
6	BRS	L6	9	("4642163"   "4867839"   "5011066"   "5489750"   "5973406"   "6081038"   "6142609"   "6222277"   "6225702").PN.	US- PGPUB; USPAT; USOCR	2005/03/16 14:15
7	BRS	L7	53	("5642261").URPN.	USPAT	2005/03/16 14:38
8	BRS	L8	0	("6829149").URPN.	USPAT	2005/03/16 14:39

	Comments	Error Definition	Errors
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	Type	L #	Hits	Search Text	DBs	Time Stamp
9	BRS	L9	9	("5216278"   "5285352"   "5381307"   "5598036"   "5625222"   "5641946"   "5642261"   "5745986"   "5796169").PN.	US- PGPUB; USPAT; USOCR	2005/03/16 14:45
10	IS&R	L10	1	("5751198").PN.	USPAT	2005/03/16 14:59
11	BRS	L11	339	andoh.inv.	USPAT	2005/03/16 15:00
12	BRS	L12	13	("5285352"   "5583377"   "5642261"   "5741729"   "5825628"   "5942795"   "5959356"   "6008536"   "6023098"   "6034427"   "6038137"   "6117705"   "6125042").PN.	US- PGPUB; USPAT; USOCR	2005/03/16 15:06
13	BRS	L13	6	("6282094").URPN.	USPAT	2005/03/16 15:07
14	BRS	L14	111	(semiconductor or chip or die) and ((bump or ball) same heat same (solid same melt\$3))	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2005/03/16 15:32
15	BRS	L15	1	(semiconductor or chip or die) and ((bump or ball) same heat same (shorting same melt\$3))	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2005/03/16 15:33
16	BRS	L16	40	(semiconductor or chip or die) and ((bump or ball) same (shorting same melt\$3))	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2005/03/16 15:35

	Comments	Error Definition	Errors
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	Type	L #	Hits	Search Text	DBs	Time Stamp
17	BRS	L17	706	(semiconductor or chip or die) and ((bump or ball) same (together same melt\$3))	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2005/03/16 15:38
18	BRS	L18	2	(semiconductor or chip or die) and ((bump or ball) same (thermally adj conductive) same (together same melt\$3))	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2005/03/16 15:44
19	BRS	L19	253	17 and cooling	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2005/03/16 15:38
20	BRS	L20	234	19 not 2	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2005/03/16 15:38
21	BRS	L21	9	(semiconductor or chip or die) and ((bump or ball) same (thermally adj conductive) same melted)	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2005/03/16 15:44

	Comments	Error Definition	Errors
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